

L Number	Hits	Search Text	DB	Time stamp
1	9	wafer with encapsulat\$3 with dic\$3 with srib\$3	USPAT; US-PGPUB	2003/06/28 14:27
2	289	wafer with encapsulat\$3 with (dic\$3 or srib\$3)	USPAT; US-PGPUB	2003/06/28 14:32
3	1	("6403449").PN.	USPAT; US-PGPUB	2003/06/28 14:34
4	55187	warp\$3	USPAT; US-PGPUB	2003/06/28 14:34
5	501984	resin or encapsulat\$3	USPAT; US-PGPUB	2003/06/28 14:34
6	2568	warp\$3 with (resin or encapsulat\$3)	USPAT; US-PGPUB	2003/06/28 14:35
7	58469	dic\$3	USPAT; US-PGPUB	2003/06/28 14:35
8	178	(warp\$3 with (resin or encapsulat\$3)) and dic\$3	USPAT; US-PGPUB	2003/06/28 14:35
9	267	(resin or encapsulat\$3) with via with solder	USPAT; US-PGPUB	2003/06/28 15:29
10	418111	@ad>20010200 @rlad>20010200	USPAT; US-PGPUB	2003/06/28 15:30
11	148	((resin or encapsulat\$3) with via with solder) not (@ad>20010200 @rlad>20010200)	USPAT; US-PGPUB	2003/06/28 15:30
-	65379	438/\$.ccls.	USPAT; US-PGPUB	2003/06/01 18:14
-	463378	semiconductor or ic or "integrated circuit" or microelectronic	USPAT; US-PGPUB	2003/05/29 17:11

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